### 30V N-Channel Enhancement Mode MOSFET

Voltage

ΡΛΝ

Current 75 A

#### Features

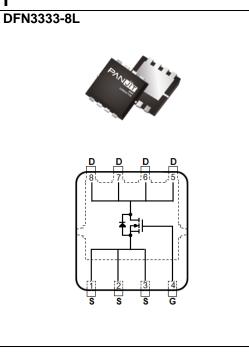
•  $R_{DS(ON)}$ ,  $V_{GS}@10V$ ,  $I_D@10A<4.2m\Omega$ 

30 V

- $R_{DS(ON)}$ ,  $V_{GS}@4.5V$ ,  $I_D@6A<7m\Omega$
- Excellent FOM
- Logic Level Drive
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

#### **Mechanical Data**

- Case : DFN3333-8L Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.03 grams



#### **Maximum Ratings and Thermal Characteristics** (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	
Drain-Source Voltage		V <sub>DS</sub>	30	V
Gate-Source Voltage		V <sub>GS</sub>	±20	
Continuous Drain Current <sup>(Note 3)</sup>	Tc=25°C		75	
	Tc=100°C	ID	48	А
Pulsed Drain Current <sup>(Note 1)</sup>	T <sub>C</sub> =25°C	I <sub>DM</sub>	300	
Power Dissipation	T <sub>C</sub> =25°C	D.	38	
	Tc=100°C	PD	15.2	W
Continuous Drain Current <sup>(Note 4)</sup>	T <sub>A</sub> =25 <sup>°</sup> C		17.6	٨
	T <sub>A</sub> =70°C	I <sub>D</sub>	14	A
Power Dissipation	T <sub>A</sub> =25°C	Po	2.1	w
	T <sub>A</sub> =70 <sup>°</sup> C	PD	1.3	VV
Single Pulse Avalanche Energy <sup>(Note 5)</sup>		Eas	42	mJ
Operating Junction and Storage Temperature Range		T <sub>J</sub> ,T <sub>STG</sub>	-55~150	°C
Thermal Resistance <sup>(Note 4)</sup>	Junction to Case	R <sub>θJC</sub>	3.3	°C/W
	Junction to Ambient	R <sub>0JA</sub>	60	C/VV



#### Electrical Characteristics (TA=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static		-					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	Vgs=0V, Id=250uA	30	-	-	V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.3	1.7	2.5		
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	3.5	4.2	4.2	
		/ <sub>GS</sub> =4.5V, I <sub>D</sub> =6A -		5.4	7	mΩ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	±1	uA	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA	
Dynamic <sup>(Note 6)</sup>							
Total Gate Charge	Qg		-	21	-	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}=24V, I_{D}=10A,$	-	3.6	-		
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V <sup>(Note 2,3)</sup>	-	3.2	-		
Input Capacitance	Ciss		-	1260	-	pF	
Output Capacitance	Coss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V,	-	560	-		
Reverse Transfer Capacitance	Crss	f=1MHz	-	44	-		
Gate resistance	Rg	f=1MHz	-	0.85	-	Ω	
Turn-On Delay Time	td <sub>(on)</sub>		-	15	-		
Turn-On Rise Time	tr	$V_{DS}=24V, I_D=10A,$	-	26	-	-	
Turn-Off Delay Time	td <sub>(off)</sub>	V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω (Note 2,3)	-	24	-	ns	
Turn-Off Fall Time	tf	(11018 2,3)	-	5	-		
Drain-Source Diode		·					
Diode Forward Current	Is	T 0500	-	-	75	A	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> =25°C	-	-	300		
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	-	0.85	1.1	V	
Reverse Recovery Time	Trr	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	31	-	ns	
Reverse Recovery Charge	Qrr	dls/dt=100A/us <sup>(Note 2,3)</sup>	-	19	-	nC	

NOTES :

- 1. Pulse width100us, Duty cycle<2%.</td>
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R\_{\rm BJC}=3.3^{\circ}C/W.
- 4.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH,  $I_{AS}$ =13A,  $V_{DD}$ =30V,  $V_{GS}$ =10V, Starting  $T_J$ =25°C. the chip is about to carry  $I_{AS}$ ≈26A.
- 6. Guaranteed by design, not subject to production testing.



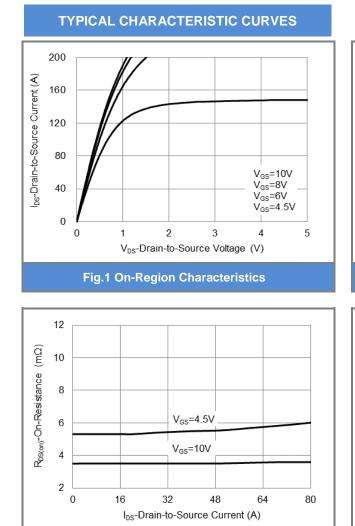
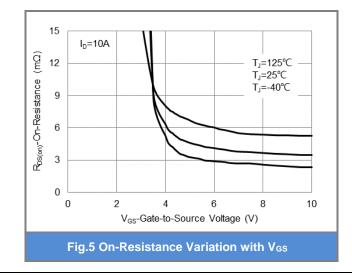
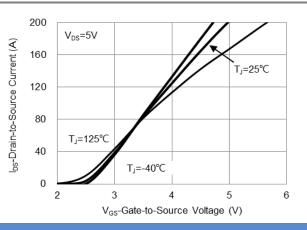


Fig.3 On-Resistance vs. Drain Current





**Fig.2 Transfer Characteristics** 

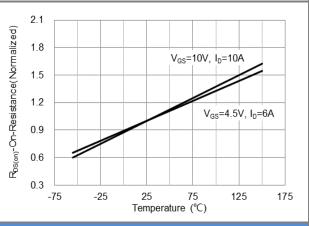
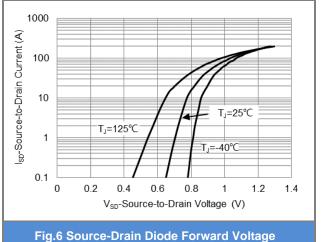
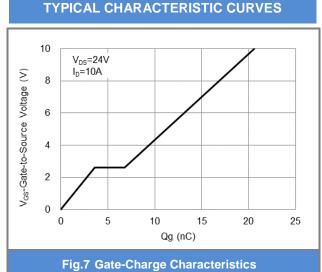


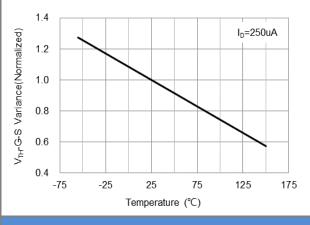
Fig.4 On-Resistance vs. Junction temperature



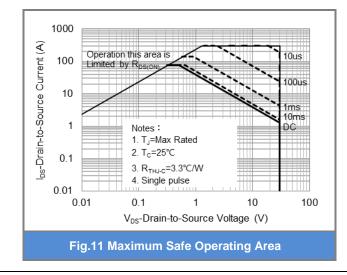


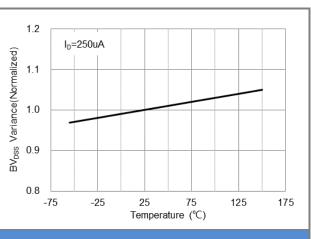














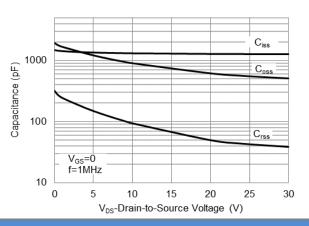
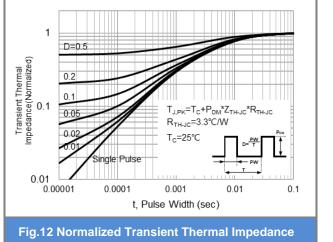


Fig.10 Capacitance vs. Drain-Source Voltage

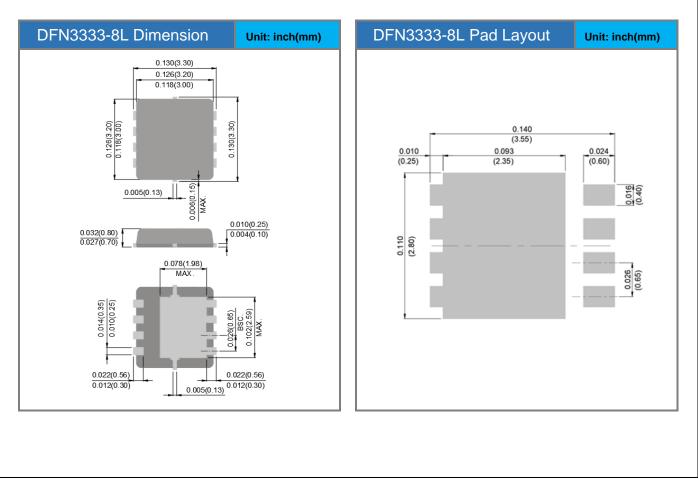




#### **Product and Packing Information**

Part No.	Package Type	Packing Type	Marking	
PJQ4524P	DFN3333-8L	5K pcs / 13" reel	4524	

### Packaging Information & Mounting Pad Layout





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